

EVG announces NanoCleave new technology revolutionizing 3D stacking technology – January 30, 2024

EVG introduced NanoCleave™, a revolutionary layer release technology for silicon that enables ultra-thin layer stacking for front-end processing, including advanced logic, memory and power device formation, as well as semiconductor advanced packaging. NanoCleave enables silicon wafer carriers in advanced packaging processes such as FoWLP using mold and reconstituted wafers as well as interposers for 3D SIC. At the same time, its compatibility with high-temperature processes enables completely novel process flows for 3D IC and 3D sequential integration applications – enabling hybrid and fusion bonding even of ultra-thin layers on silicon carriers, thereby revolutionizing 3D and heterogeneous integration as well as material transfer in next-generation scaled transistor designs.



News article layout with title: EVG, 3D 적층 기술 혁신하는 '나노클리브' 신기술 발표. Subtitle: 기존 유리 기반 사용을 실리콘 웨이퍼로 대체 가능. Author: 장경준 기자. Includes a photo of a factory floor with equipment.

EVG의 나노클리브 광배사선(EV3)
또한 나노클리브는 반도체 전 공정에 광배사선 초정밀 레이저 마스크를, 실리콘을 통과하는 적외선 레이저를 사용하는 것이 특징이다....

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